

## Application - News N°388 L-LAS series

Sensor Let's make sensors more individual

Instruments

## 1. Wafer edge detection

PARA1 PARA2 REC CALIB

211

POWER-MODE STEACH-VALUE (Pixel)

EEPROM

PARA II: GENERAL-PARAMETER

**\$**1

V-THD[%]

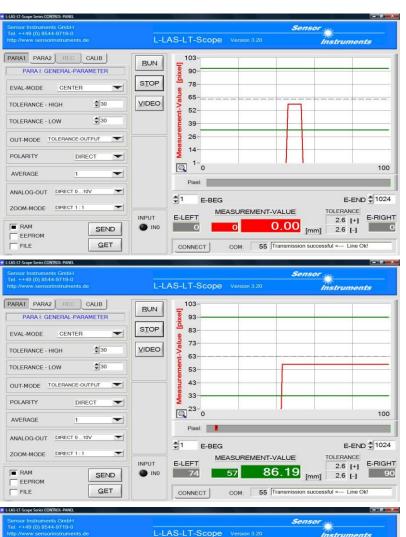
**1**5

Teach

SEND

GET

The edges of wafers with a thickness of 80  $\mu$ m should be detected. For this purpose a laser displacement sensor type **L-LAS-LT-110-HD2** is used. The distance of the sensor to the wafer edges is around 90mm and the laser spot size at this distance is around 50  $\mu$ m. The edges can be proper detected as shown in the screen shots.



1024-

800

700-600-

500-400-300-

200-

‡1

70

CONNECT

Pixel:

86.19 [mm] 2.6 [-]

55 Transmission successful <--- Line Ok!

BUN

VIDEO



